

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped Silicon	Silicon (Si)	7440-21-3	0.47604	100.0	1.1
			<b>Subtotal</b>	<b>0.47604</b>	<b>100</b>	<b>1.1</b>
Post-plating	Tin solder	Bismuth (Bi)	7440-69-9	0	0.0	0
	Tin solder	Tin (Sn)	7440-31-5	1.59242	99.99	3.67963
	Tin solder	Copper (Cu)	7440-50-8	0	0.0	0
	Tin solder	Lead (Pb)	7439-92-1	0.00016	0.01	0.00037
	Tin solder	Antimony (Sb)	7440-36-0	0	0.0	0
			<b>Subtotal</b>	<b>1.59258</b>	<b>100</b>	<b>3.68</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01199	0.03	0.02772
	Copper alloy	Iron (Fe)	7439-89-6	0.03998	0.1	0.09239
	Copper alloy	Copper (Cu)	7440-50-8	39.82328	99.6	92.02044
	Pure metal layer	Silver (Ag)	7440-22-4	0.10795	0.27	0.24945
			<b>Subtotal</b>	<b>39.9832</b>	<b>100</b>	<b>92.39</b>
Adhesive	Polymer	Paraffin wax	8002-74-2	0.18522	20.0	0.428
	Polymer	Epoxy resin system		0.07409	8.0	0.1712
	Filler	Silver (Ag)	7440-22-4	0.66681	72.0	1.5408
			<b>Subtotal</b>	<b>0.92612</b>	<b>100</b>	<b>2.14</b>
Mould Compound	Polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	1.4251	2.5	3.293
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	4.27529	7.5	9.879
	Filler	Silica -amorphous-	7631-86-9	21.09143	37.0	48.7364
	Pigment	Carbon black	1333-86-4	0.28502	0.5	0.6586
	Polymer	Epoxy resin system		8.55058	15.0	19.758
	Filler	Silicon Dioxide (SiO2)	14808-60-7	21.09143	37.0	48.7364
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.28502	0.5	0.6586
			<b>Subtotal</b>	<b>57.00387</b>	<b>100</b>	<b>131.72</b>
Wire	Copper alloy	Copper (Cu)	7440-50-8	0.01818	100.0	0.042
			<b>Subtotal</b>	<b>0.01818</b>	<b>100</b>	<b>0.042</b>
			<b>Total</b>	<b>99.99999</b>	<b>100</b>	<b>231.072</b>

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